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- Member of the Texas Instruments
  Widebus™ Family
- EPIC ™ (Enhanced-Performance Implanted CMOS) Submicron Process
- Typical V<sub>OLP</sub> (Output Ground Bounce)
  < 0.8 V at V<sub>CC</sub> = 3.3 V, T<sub>A</sub> = 25°C
- Typical V<sub>OHV</sub> (Output V<sub>OH</sub> Undershoot)
  2 V at V<sub>CC</sub> = 3.3 V, T<sub>A</sub> = 25°C
- Bus-Hold on Data Inputs Eliminates the Need for External Pullup/Pulldown Resistors
- Package Options Include Plastic 300-mil Shrink Small-Outline (DL) and Thin Shrink Small-Outline (DGG) Packages

#### description

This 16-bit buffer/driver is designed for 2.7-V to  $3.6\text{-V}\ \text{V}_{CC}$  operation.

The SN74LVC16244 is designed specifically to improve both the performance and density of 3-state memory address drivers, clock drivers, and bus-oriented receivers and transmitters.

The device can be used as four 4-bit buffers, two 8-bit buffers, or one 16-bit buffer. It provides true outputs and symmetrical active-low output-enable  $(\overline{OE})$  inputs.

Active bus-hold circuitry is provided to hold unused or floating data inputs at a valid logic level.

The SN74LVC16244 is characterized for operation from -40°C to 85°C.

## DGG OR DL PACKAGE (TOP VIEW)

		_		1	
10E	1	$\cup$	48	þ	2OE
1Y1 [	2		47		1A1_
1Y2 [	3		46	þ	1A2
GND [	4		45	þ	GND
1Y3 [	5		44	1	1A3
1Y4 [	6		43	1	1A4
V <sub>CC</sub> [	7		42	1	$V_{CC}$
2Y1 [	8		41	1	2A1
2Y2 [	9		40	þ	2A2
GND [	10		39	þ	GND
2Y3 [	11		38	1	2A3
2Y4 [	12		37	þ	2A4
3Y1 [	13		36	þ	3A1_
3Y2 [	14		35	þ	3A2
GND [	15		34	þ	GND
3Y3 [	16		33	1	3A3
3Y4 [	17		32	1	3A4
V <sub>CC</sub> [	18		31	1	$V_{CC}$
4Y1 [	19		30	þ	4A1
4Y2 [	20		29	þ	4A2
GND [	21		28	þ	GND
4Y3 [	22		27	þ	4A3
4Y4 [	23		26		4A4
40E	24		25		3OE
	_	-	_	J	

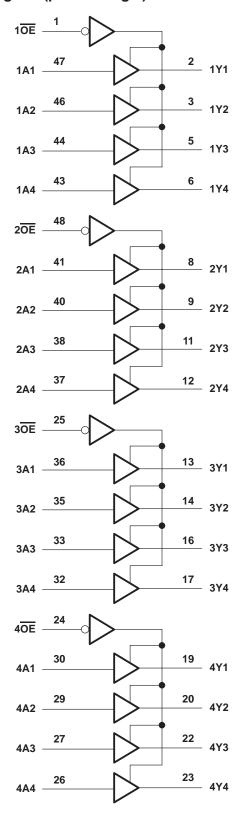
# FUNCTION TABLE (each 4-bit buffer)

INPUTS		OUTPUT
OE	Α	Υ
L	Н	Н
L	L	L
Н	Χ	Z

#### logic symbol†

#### 1 EN1 10E 48 2OE EN2 25 3OE EN3 24 4OE EN4 47 2 1 ▽ 1Y1 1A1 3 46 1A2 1Y2 5 44 1A3 1Y3 43 6 1A4 1Y4 41 8 2 ▽ 1 2A1 2Y1 9 40 2A2 2Y2 38 11 2A3 2Y3 37 12 2A4 2Y4 13 1 3 ▽ 3A1 3Y1 35 14 3A2 3Y2 33 16 3A3 3Y3 32 17 3A4 3Y4 30 19 1 4 ▽ 4A1 4Y1 29 20 4A2 4Y2 27 22 4Y3 4A3 26 4A4 4Y4

### logic diagram (positive logic)





<sup>†</sup> This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

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#### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V <sub>CC</sub>		0.5 V t	o 4.6 V
Input voltage range, V <sub>I</sub> (see Note 1)		0.5 V t	o 4.6 V
Output voltage range, VO (see Notes 1 and 2)	0.5 V to	o V <sub>CC</sub>	+ 0.5 V
Input clamp current, $I_{IK}$ ( $V_I < 0$ )			-50 mA
Output clamp current, $I_{OK}$ ( $V_O < 0$ or $V_O > V_{CC}$ )		±	50 mA
Continuous output current, $I_O(V_O = 0 \text{ to } V_{CC})$		±	50 mA
Continuous current through V <sub>CC</sub> or GND		±1	100 mA
Maximum power dissipation at $T_A = 55^{\circ}C$ (in still air) (see Note 3):	DGG package		0.85 W
	DL package		1.2 W
Operating free-air temperature range, T <sub>A</sub>		-40°C t	to 85°C
Storage temperature range	6	65°C to	150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
  - 2. This value is limited to 4.6 V maximum.
  - 3. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils. For more information, refer to the *Package Thermal Considerations* application note in the 1994 *ABT Advanced BiCMOS Technology Data Book*, literature number SCBD002B.

#### recommended operating conditions (see Note 4)

			MIN	NOM	MAX	UNIT
Vcc	Supply voltage		2.7	3.3	3.6	V
VIH	High-level input voltage	V <sub>CC</sub> = 2.7 V to 3.6 V	2			V
VIL	Low-level input voltage	V <sub>CC</sub> = 2.7 V to 3.6 V			0.8	V
٧ <sub>I</sub>	Input voltage		0		Vcc	V
VO	Output voltage		0		Vcc	V
ЮН	High-level output current	V <sub>CC</sub> = 2.7 V			-12	mA
		V <sub>CC</sub> = 3 V			-24	IIIA
IOL	l ann land antent anneat	V <sub>CC</sub> = 2.7 V			12	A
	Low-level output current	V <sub>CC</sub> = 3 V			24	mA
Δt/ΔV	Input transition rise or fall rate		0		10	ns/V
TA	Operating free-air temperature		-40		85	°C

NOTE 4: Unused or floating control pins must be held high or low.

#### SN74LVC16244 **16-BIT BUFFER/DRIVER WITH 3-STATE OUTPUTS**

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#### electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	v <sub>cc</sub>	MIN	TYP†	MAX	UNIT	
V		$I_{OH} = -100  \mu A$	MIN to MAX‡	V <sub>CC</sub> -0	.2			
		I <sub>OH</sub> = -12 mA	2.7	2.2			V	
VOH		10H = - 12 IIIA	3	2.4			v	
		$I_{OH} = -24 \text{ mA}$	3	2				
		I <sub>OL</sub> = 100 μA	MIN to MAX‡			0.2		
VOL		I <sub>OL</sub> = 12 mA	2.7			0.4	V	
		I <sub>OL</sub> = 24 mA	3			0.55		
II		$V_I = V_{CC}$ or GND	3.6			±5	μΑ	
lia i s	Data inpute	V <sub>I</sub> = 0.8 V	3	75			μА	
I(hold)	Data inputs	V <sub>I</sub> = 2 V		-75			μΑ	
loz		$V_O = V_{CC}$ or GND	3.6			±10	μΑ	
ICC		$V_I = V_{CC}$ or GND, $I_O = 0$	3.6			40	μΑ	
ΔICC		$V_{CC} = 3 \text{ V to } 3.6 \text{ V},$ One input at $V_{CC} - 0.6 \text{ V},$ Other inputs at $V_{CC}$ or GND				500	μΑ	
Ci		$V_I = V_{CC}$ or GND	3.3		2.5		pF	
Co		$V_O = V_{CC}$ or GND	3.3		3.5		pF	

# switching characteristics over recommended ranges of supply voltage and operating free-air temperature, $C_L$ = 50 pF (unless otherwise noted) (see Figure 1)

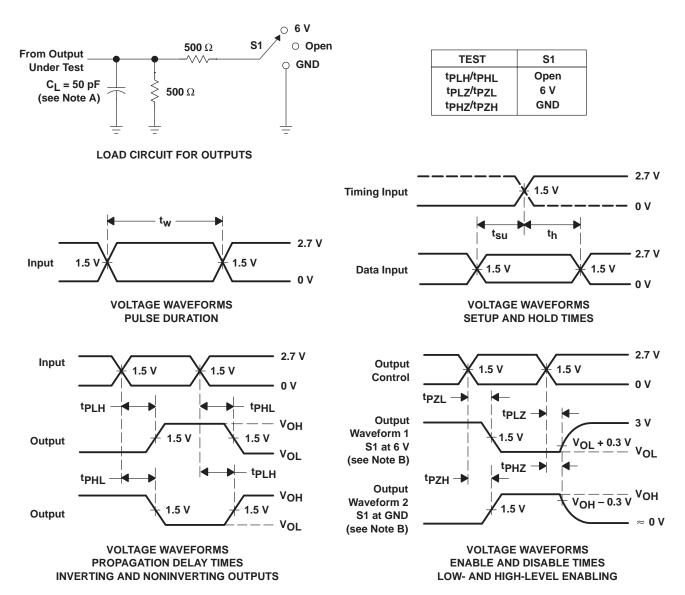
PARAMETER	FROM	то	$V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$			V <sub>CC</sub> = 2.7 V		UNIT
	(INPUT)	(OUTPUT)	MIN	TYP†	MAX	MIN	MAX	UNIT
<sup>t</sup> pd	А	Υ	1.5	4.2	6.5		7.5	ns
t <sub>en</sub>	ŌĒ	Υ	1.5	4.4	8		9	ns
<sup>t</sup> dis	ŌĒ	Υ	1.5	4.4	7		8	ns

<sup>&</sup>lt;sup>†</sup> All typical values are at  $V_{CC} = 3.3 \text{ V}$ ,  $T_A = 25^{\circ}\text{C}$ .



<sup>†</sup> All typical values are at  $V_{CC}$  = 3.3 V,  $T_A$  = 25°C. ‡ For conditions shown as MIN or MAX, use the appropriate values under recommended operating conditions.

#### PARAMETER MEASUREMENT INFORMATION



NOTES: A. C<sub>I</sub> includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_O = 50 \ \Omega$ ,  $t_f \leq 2.5 \ ns$ .
- D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms



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